

Atomically precise Si(331)-(12×1) surfaces

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Abstract. Si(331)-(12×1) is the only confirmed planar silicon surface with a stable reconstruction located between (111) and (110). We have optimized the annealing sequence and are able to obtain almost defect free, atomically precise surface areas approaching micrometer dimensions. The unprecedented perfection of the surface combined with its pronounced structural anisotropy makes it a promising candidate to serve as template for the growth of self-assembled one-dimensional nanostructure arrays.

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The fabrication of atomically precise nanostructure arrays on semiconductor surfaces remains a challenging task. A narrow size distribution and controlled positioning are essential in view of applications, since fluctuations of only a few atoms may substantially alter the electronic and optoelectronic properties. Spontaneous self-assembly represents a promising bottom-up approach allowing production of nanostructures in a massively parallel fashion. However, the uniformity often suffers from relatively large variations and the spatial arrangements are hard to control.

A prototypical example for atomically precise self-assembled nanostructures are semiconductor surface reconstructions, which form not only on clean surfaces [1], but may also be stabilized by foreign adsorbate species [2, 3]. They are ideal templates for the growth of more complex atomically precise structures such as magic clusters exhibiting enhanced stability at certain magic sizes. Atomically precise periodic surfaces, such as the Si(111)-(7×7) reconstruction, have been used successfully to grow perfectly ordered arrays of such identical-size clusters [4].

Here we focus on the Si(331)-(12×1) reconstruction, whose surface normal is located 22° away from the (111) direction towards (110). Based on scanning tunneling microscopy (STM) images of unprecedented resolution, we were recently able to resolve for the first time double rows of silicon pentamers on this surface (see Fig. 1) [5]. Combining our STM images with low energy electron diffraction data and first-principles total energy calculations allowed us to propose a new structural model.

Surface preparation is crucial if one wants to study structural and electronic properties at the atomic scale. Here we describe in more detail our optimized sample preparation process. Using an automated system, Si(331)-(12×1) surfaces of very high quality are prepared rou-

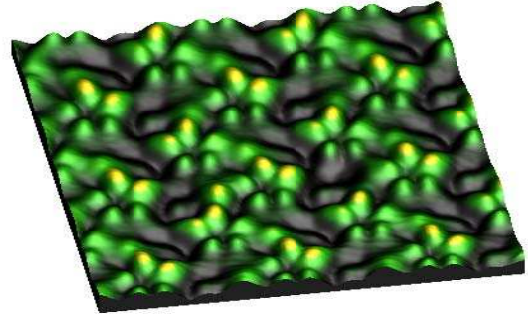


FIGURE 1. (Color online) 3D rendered high-resolution STM topography of the Si(331)-(12×1) reconstruction. Bias voltage 2.0 V, set-point current 0.06 nA, size 7 nm × 5 nm, temperature 77 K.

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Boron doped Si(331) samples from Crystec with a resistivity of 0.1-30 Ω cm were used in this work. The reconstruction of the Si(331) surface is highly sensitive to small amounts of Ni contamination changing the periodicity from (12×1) to (13×1). To avoid Ni contamination, any contact of silicon with stainless steel must be avoided. Silicon samples and the Mo sample holders are exclusively handled with teflon tweezers and Mo tools. All samples are first cleaned for 5 minutes in an acetone ultrasound bath followed by an ethanol ultrasound bath for another 5 minutes. Coming out of the ethanol bath, the samples are dry blown with clean nitrogen gas, mounted on the Mo holder and transferred into vacuum. During the first preparation step in vacuum, the sample is degassed by passing a direct current through the sample. In our setup a pressure signal from the gauge controller is sent into a feedback loop which controls the sample current while keeping the pressure below 5×10^{-10} mbar.

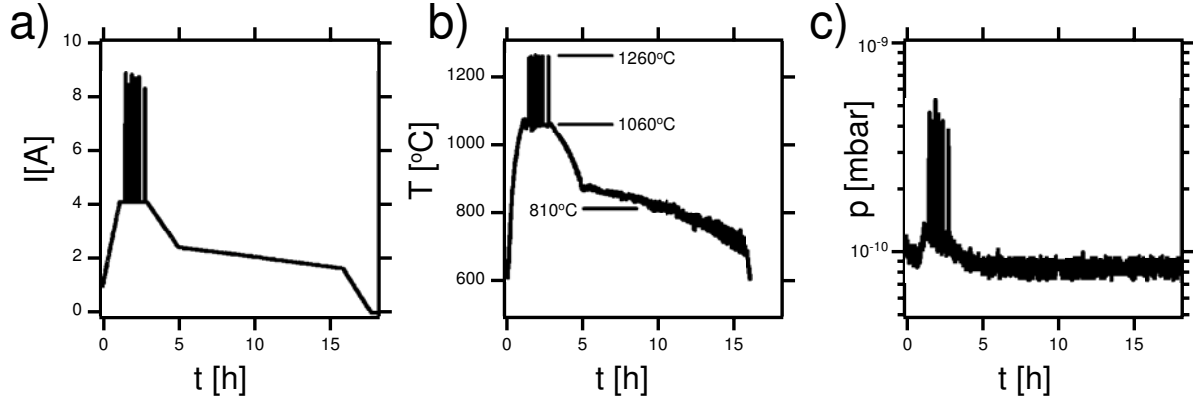


FIGURE 2. Typical preparation cycle for a Si(331) surface. a) current vs time, b) temperature vs time, c) pressure vs time.

Once the sample temperature attains 1060°C, the sample is flashed repeatedly to 1260°C. The ramp from 1060°C to 1260°C is performed within 2 seconds, the cool-down back to 1060°C is completed within 10 seconds during the first flashes in order to keep the pressure during the entire flash below 2×10^{-9} mbar. The cool-down period during the final flashes is 30 s. At 1060°C single steps on Si(111) have been reported to be stable [6] and we find it to be an ideal base temperature to perform flashing to higher temperature, since it is above the transition temperature for all known silicon surface reconstructions. The stress on the wafer, induced by the fixation to the sample holder, should be minimized to allow the sample to expand freely upon heating.

The cool-down sequence which follows is crucial for the quality and long range order of the surface reconstruction. Ideally one would like to keep the sample for a certain period at the transition temperature, where the surface reconstruction forms, to allow long range order to be established. However, transition temperatures reported in the literature are usually accurate to within only 20°C to 30°C. Additional uncertainties arise due to the difficulty to obtain an absolute calibration for our own pyrometer which works at a single wave length. Uncertainties due to value of the selected emissivity should also not be forgotten. All our measurements on silicon surfaces were carried out using an emissivity ϵ of 0.65.

Our cool-down strategy is simple, but yet highly effective. Instead of annealing the sample at a fixed temperature, we start the annealing sequence at about 50°C above the transition temperature, which was reported to be at 810°C [7], and slowly cool the sample down to a temperature of about 50°C below the transition temperature typically within 12 h. The slow cool-down rate guarantees that the sample spends enough time close to the transition temperature to optimize its long range order. Sample preparation is completed by a cool-down of 2 h down to room temperature. With this method we are able

to obtain almost defect free, atomically precise Si(331)-(12×1) surfaces over areas approaching micrometer dimensions.

Fig. 2 shows the preparation cycle for the Si(331) surface. For process control purposes it is useful to record not only the current a) and the temperature b) of the sample as a function of time but also the pressure c) during the entire preparation cycle. The three automated steps of the preparation cycle, degassing, flashing and cool-down including annealing, can be clearly distinguished in all three traces. Note that the Si(331)-(12×1) reconstruction forms at a temperature of 810°C, which lies approximately in the middle of the annealing temperature range.

In summary we have described the preparation process for obtaining high quality Si(331)-(12×1) surfaces for which we recently proposed a new structural model.

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